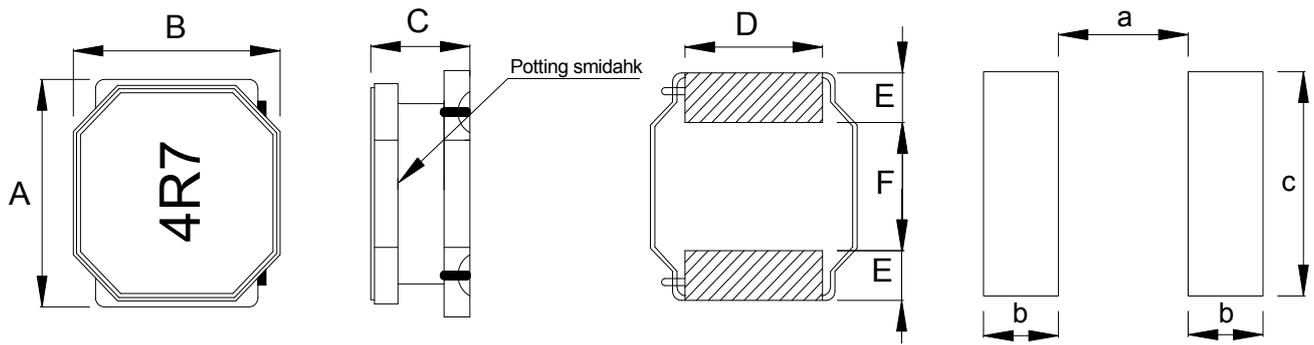


### 1. External Dimensions (Unit:m/m)



Type	A	B	C	D	E	F	a	b	c	Q'TY/Reel
ABG03A15	3.0±0.2	3.0±0.2	1.7Max	2.55Ref	0.9Ref	1.2Ref	0.9Ref	1.2Ref	3.1Ref	2000

### 2. Part Number Code

ABG    03    A    15    N    4R7  
 A        B        C        D        E        F

A: Series Name                      Power Inductors  
 B: Dimensions(mm)                03: 3.0x3.0  
 C: Materials                         NO use  
 D: Thickness(mm)                 15: 1.7 Max  
 E: Tolerance                         N: ±30%  
 F: Inductance                        4R7=4.7uH

### 3. Electrical Characteristics

Part Number	Inductance (μH)	Test Frequency (KHz)	DC Resistance (mΩ) ±30%	Heat Rating Current Irms (A)	Saturation Current Isat (A)
ABG03A15N4R7	4.7	100KHz/1V	123.0	1.09	1.1

Notes:

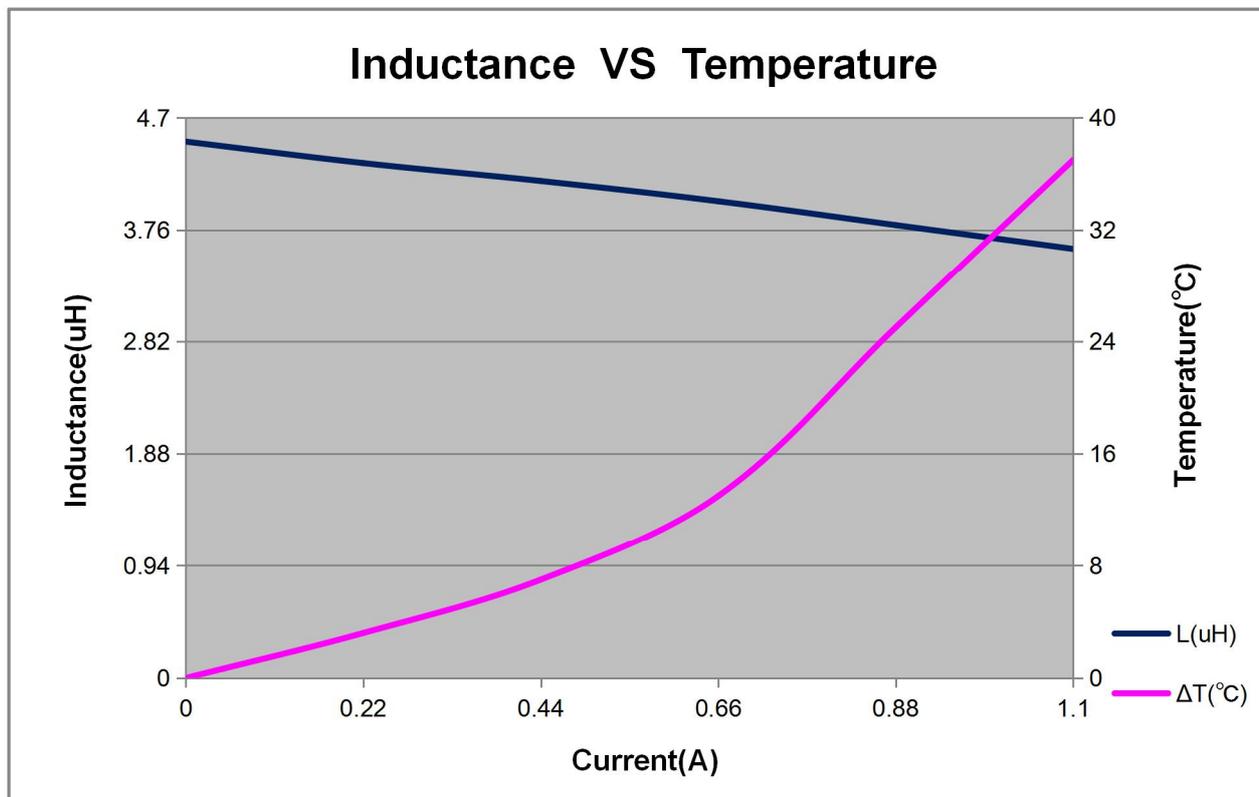
- 1) All test data is referenced to 25°C ambient.
- 2) Operating temperature range -40°C to +125°C.
- 3) Irms :DC current(A) that will cause an approximate ΔT of 40°C.
- 4) Isat :DC current(A) that will cause I<sub>o</sub> to drop approximately 35%.
- 5) The part temperature(ambient + temp rise)should not exceed 125°C under worst case operating conditions. Circuit design,component placement, PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature,part temperature should be verified in the end application.

### 4. Test Data

ELECTRICAL CHARACTERISTIC				MECHANICAL DIMENSIONS			
SPEC	L(uH)	DCR(mΩ)	Isat(uH)	A(mm)	B(mm)	C(mm)	D(mm)
TOL	4.7	123.0	1.1A	3.0	3.0	1.7	2.55
NO	±30%	±30%	(LOA-L1.1A) /LOA≤35%	±0.2	±0.2	Max	Ref
1	4.52	128.6	3.62	3.02	3.03	1.34	OK
2	4.48	127.9	3.59	3.04	3.01	1.36	OK
3	4.53	130.2	3.63	3.03	3.02	1.37	OK
4	4.51	129.4	3.61	3.01	3.03	1.34	OK
5	4.49	127.5	3.60	3.03	3.02	1.35	OK
6	4.47	128.7	3.58	3.02	3.00	1.36	OK
7	4.54	131.8	3.64	3.02	3.02	1.35	OK
8	4.51	129.4	3.61	3.01	3.01	1.37	OK
9	4.55	127.3	3.65	3.02	3.02	1.35	OK
10	4.48	128.2	3.59	3.03	3.01	1.36	OK

Test Equipments: IM3536,VR126,VR7210,Calipers

Curve:



## 5. Test and Measurement Procedures

### 5.1 Test Conditions

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- Ambient Temperature:  $20 \pm 15^\circ\text{C}$
- Relative Humidity:  $65\% \pm 20\%$
- Air Pressure: 86KPa to 106KPa

5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:

- Ambient Temperature:  $20 \pm 2^\circ\text{C}$
- Relative Humidity:  $65\% \pm 5\%$
- Air Pressure: 86KPa to 106Kpa

### 5.2 Visual Examination

- Inspection Equipment: 10X magnifier

### 5.3 Electrical Test

5.3.1 Inductance (L)

- Refer to the third item.
- Test equipment: IM3536 LCR meter or equivalent.
- Test Frequency and Voltage: Refer to the third item.

5.3.2 Direct Current Resistance (DCR)

- Refer to the third item.
- Test equipment: VR126 or equivalent.

5.3.3 Saturation Current ( $I_{\text{sat}}$ )

- Refer to the third item.
- Test equipment: Saturation current meter
- Definition of saturation current ( $I_{\text{sat}}$ ): DC current at which the inductance drops approximate 35% from its value without current.

5.3.4 Temperature rise current ( $I_{\text{rms}}$ )

- Refer to the third item.
- Test equipment (see Fig.5.3.4-1): Electric Power, Electric current meter, Thermometer.
- Measurement method (see Fig. 5.3.4-1):
  - Set test current to be 0mA.
  - Measure initial temperature of choke surface.
  - Gradually increase current and measure choke temperature for corresponding current.
  - Definition of Temperature rise current: DC current that causes the temperature rise ( $\Delta T = 40^\circ\text{C}$ ) from  $20^\circ\text{C}$  ambient (see Fig. 5.3.4-2).

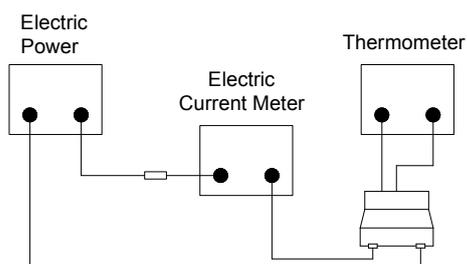


Fig.5.3.4-1

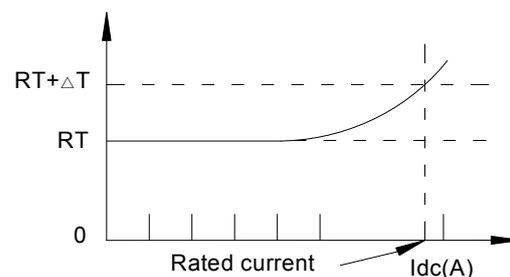
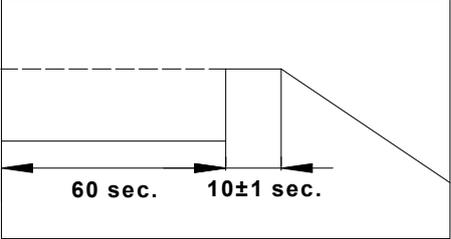
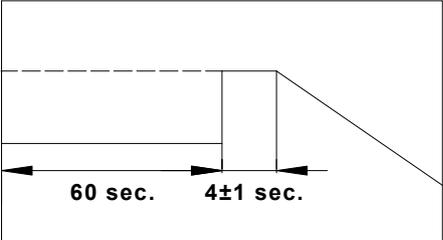


Fig.5.3.4-2

### 5.4 Reliability Test

Item	Specifications	Test conditions
5.4.1 High temperature storage test	No visible mechanical damage. Inductance change: Within $\pm 10\%$ .	<p>Temperature: <math>125 \pm 2^\circ\text{C}</math>. Duration: 500hrs. Measured at room temperature after placing for <math>24 \pm 4</math> hrs.</p>
5.4.2 Temperature cycling test	No visible mechanical damage. Inductance change: Within $\pm 10\%$ .	<p>Condition for 1 cycle. Step1: <math>-40 \pm 2^\circ\text{C}</math> 30min Min. Step2: <math>125 \pm 2^\circ\text{C}</math>, transition time 2min Max. Step3: <math>125 \pm 2^\circ\text{C}</math> 30min Min. Step4: Low temp, transition time 2min Max. Number of cycles: 100. Measured at room temperature after placing for <math>24 \pm 4</math> hrs.</p>
5.4.3 Biased humidity test	No visible mechanical damage. Inductance change: Within $\pm 10\%$ .	<p>Humidity : <math>85\% \pm 3</math> RH. Temperature: <math>60^\circ\text{C} \pm 2^\circ\text{C}</math>. Duration : 500hrs. Measured at room temperature after placing for <math>24 \pm 4</math> hrs.</p>
5.4.4 Operational life test	No visible mechanical damage. Inductance change: Within $\pm 10\%$ .	<p>Temperature: <math>85 \pm 2^\circ\text{C}</math>. Duration : 500hrs. Measured at room temperature after placing for <math>24 \pm 4</math> hrs.</p>
5.4.5 Resistance to solvent test	No visible mechanical damage. Inductance change: Within $\pm 10\%$ .	Add aqueous wash chemical - OKEM clean or equivalent.
5.4.6 Vibration test	No visible mechanical damage. Inductance change: Within $\pm 10\%$ .	The sample shall be soldered onto the printed circuit board and when a vibration having an amplitude of 1.52mm and a frequency of from 10 to 55Hz/1 minute repeated should be applied to the 3 directions (X,Y,Z) for 2 hours each.(A total of 6 hours)

Item	Specifications	Test conditions
<p>5.4.7 Resistance to soldering heat test</p>	<p>No visible mechanical damage. Inductance change: Within <math>\pm 10\%</math>.</p>	<p>Temperature (<math>^{\circ}\text{C}</math>): <math>260 \pm 5</math> (solder temp). Time (s): <math>10 \pm 1</math>. ramp/immersion and emersion rate: <math>25\text{mm/s} \pm 6 \text{ mm/s}</math>. Number of heat cycles: 1.</p> 
<p>5.4.8 Solderability test</p>	<p>More than 95% of the terminal electrode should be covered with solder.</p>	<p>Steam Aging: 8 hours <math>\pm</math> 15 min. Preheat: <math>150^{\circ}\text{C}</math>, 60sec. Solder: Sn99.5%-Cu0. 5%. Temperature: <math>245 \pm 5^{\circ}\text{C}</math>. Flux for lead free: Rosin. 9.5%. Dip time: <math>4 \pm 1</math>sec. Depth: completely cover the termination.</p> 
<p>5.4.9 Terminal strength (SMD) test</p>	<p>No visible mechanical damage.</p>	<p>With the component mounted on a PCB with the device to be tested, apply a 10 N force to the side of a device being tested. This force shall be applied for <math>10 \pm 1</math> seconds. Also the force shall be applied radually as not to apply a shock to the component being tested.</p>

### 6. Packaging, Storage

#### 6.1 Tape and Reel Packaging Dimensions

##### 6.1.1 Taping Dimensions (Unit: mm)

Please refer to Fig. 6.1.1-1.

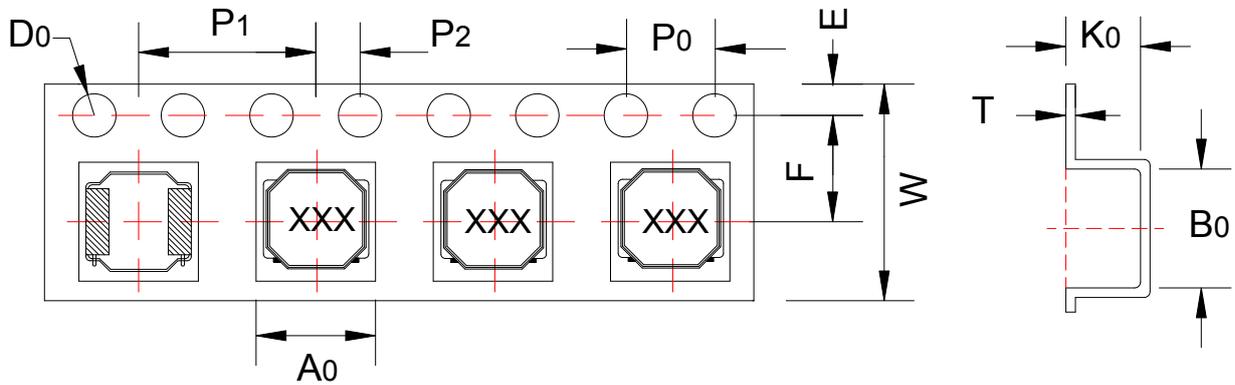


Fig. 6.1.1-1.

TYPE	A0	B0	W	E	F	P0	P1	P2	D0	T	K0
ABG03A15	3.3±0.1	3.3±0.1	8.0±0.3	1.75±0.1	3.5±0.1	4.0±0.1	4.0±0.1	2.0±0.1	1.5±0.1	0.4±0.1	1.85±0.1

##### 6.1.2 Reel Dimensions (Unit: mm)

Please refer to Fig. 6.1.2-1.

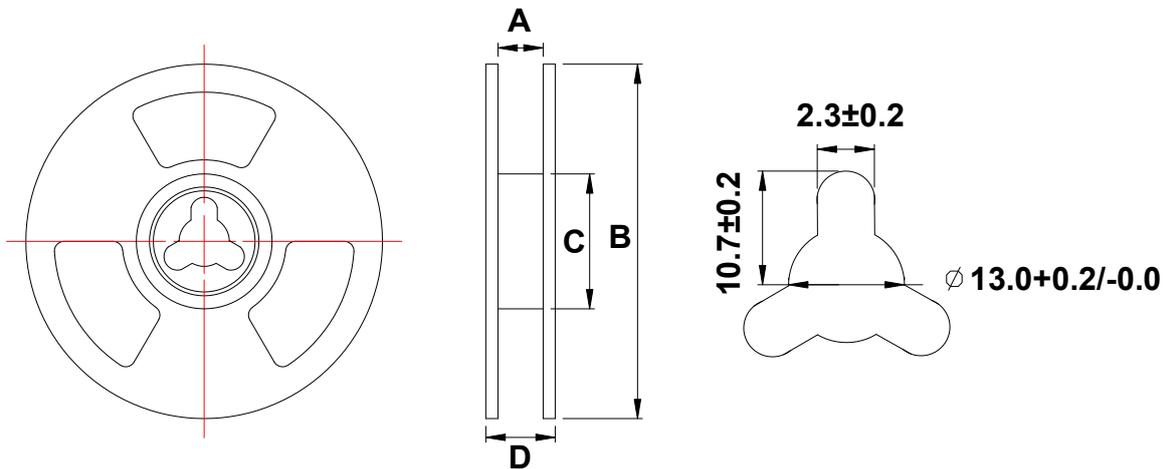


Fig. 6.1.2-1.

TYPE	A	B	C	D
ABG03A15	8.5±2.0	178.0±2.0	58.0±2.0	10.5±2.0

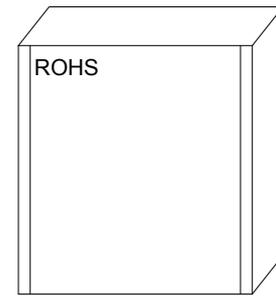
### 6.2 Packaging

6.2.1 The inner box specification: 195\*192\*65MM

Packing quantity: 10000PCS/ box.

Sealing bag: 32\*23CM

Job description: putting the air sealing bag products placed inside the box.

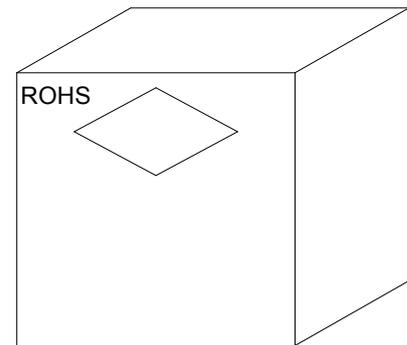


6.2.2 The outside box specification: 410\*405\*165MM

Packing quantity: 80000PCS/ box.

Job description: will be outside the box bottom sealed, inner box into the box.

- a. With transparent tape sealed box at the top.
- b. The specified location with a box labels in the outer box.
- c. If the mantissa box under a FCL with inner box for filling full.



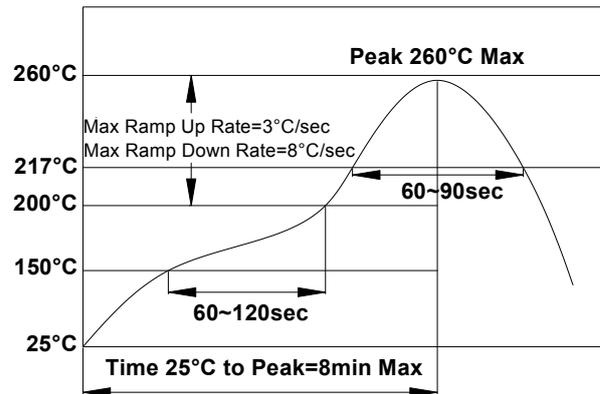
### 6.3 Storage

- a. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.
- b. Recommended conditions: -10°C~40°C, 70%RH (Max).
- c. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within one year from the time of delivery.
- d. In case of storage over one year, solderability shall be checked before actual usage.

### 7. Recommended Soldering Technologies

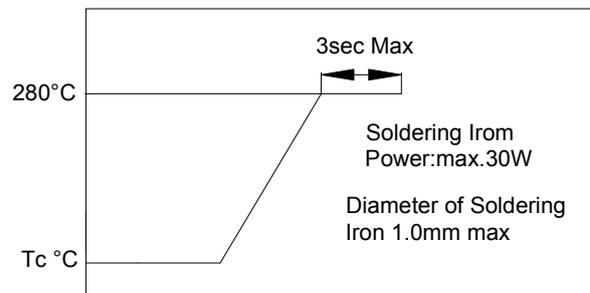
#### 7.1 Re-flowing Profile:

- △ Preheat condition: 150~200°C/60~120sec.
- △ Allowed time above 217°C: 60~90sec.
- △ Max temp: 260°C
- △ Max time at max temp: 5sec.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Allowed Reflow time: 2x max



#### 7.2 Iron Soldering Profile:

- △ Iron soldering power: Max.30W
- △ Pre-heating: 150°C/60sec.
- △ Soldering Tip temperature: 350°C Max.
- △ Soldering time: 3sec Max.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Max.1 times for iron soldering



[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]